

SLOVENSKI STANDARD
oSIST prEN IEC/IEEE 63195-1:2022
01-september-2022

Ocenjevanje gostote moči na človeku, izpostavljenem radiofrekvenčnim poljem iz brezžičnih naprav, ki so zelo blizu njegovi glavi in telesu (frekvenčno območje 6 GHz - 300 GHz) - 1. del: Merilni postopek

Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body (frequency range of 6 GHz to 300 GHz) - Part 1: Measurement procedure

Bewertung der Leistungsdichte der Exposition des Menschen gegenüber hochfrequenten Feldern von drahtlosen Geräten in unmittelbarer Nähe des Kopfes und des Körpers (Frequenzbereich von 6 GHz bis 300 GHz) - Teil 1: Messverfahren

Évaluation de la densité de puissance de l'exposition humaine aux champs radiofréquences provenant de dispositifs sans fil à proximité immédiate de la tête et du corps (plage de fréquences de 6 GHz à 300 GHz) - Partie 1: Procédure de mesure

Ta slovenski standard je istoveten z: prEN IEC/IEEE 63195-1

ICS:

17.220.20	Merjenje električnih in magnetnih veličin	Measurement of electrical and magnetic quantities
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oSIST prEN IEC/IEEE 63195-1:2022 **en,fr,de**

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

DRAFT
prEN IEC/IEEE 63195-1

June 2022

ICS 17.220.20

English Version

**Assessment of power density of human exposure to radio
frequency fields from wireless devices in close proximity to the
head and body (frequency range of 6 GHz to 300 GHz) - Part 1:
Measurement procedure
(IEC/IEEE 63195-1:2022)**

Évaluation de la densité de puissance de l'exposition
humaine aux champs radiofréquences provenant de
dispositifs sans fil à proximité immédiate de la tête et du
corps (plage de fréquences de 6 GHz à 300 GHz) -
Partie 1: Procédure de mesure
(IEC/IEEE 63195-1:2022)

Bewertung der Leistungsdichte der Exposition des
Menschen gegenüber hochfrequenten Feldern von
drahtlosen Geräten in unmittelbarer Nähe des Kopfes und
des Körpers (Frequenzbereich von 6 GHz bis 300 GHz) -
Teil 1: Messverfahren
(IEC/IEEE 63195-1:2022)

This draft European Standard is submitted to CENELEC members for enquiry.
Deadline for CENELEC: 2022-09-16.

The text of this draft consists of the text of IEC/IEEE 63195-1:2022 (106/507/CDV).

If this draft becomes a European Standard, CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

prEN IEC/IEEE 63195-1:2022 (E)**European foreword**

This document (prEN IEC/IEEE 63195-1:2022) consists of the text of document IEC/IEEE 63195-1:2022, prepared by IEC/TC 106 "Methods for the assessment of electric, magnetic and electromagnetic fields associated with human exposure".

This document is currently submitted to the Enquiry.

The following dates are proposed:

- latest date by which the existence of this document (doa) dor + 6 months has to be announced at national level
- latest date by which this document has to be (dop) dor + 12 months implemented at national level by publication of an identical national standard or by endorsement
- latest date by which the national standards (dow) dor + 36 months conflicting with this document have to be withdrawn (to be confirmed or modified when voting)

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC/IEEE 62209-1528	2020	Measurement procedure for the assessment of specific absorption rate of human exposure to radio frequency fields from hand-held and body-worn wireless communication devices - Part 1528: Human models, instrumentation and procedures (Frequency range of 4 MHz to 10 GHz)	EN IEC/IEEE 62209-1528	2021
IEC/IEEE 63195-2	2022	Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body (Frequency range of 6 GHz to 300 GHz) – Part 2: Computational procedure	EN IEC/IEEE 63195-2	— ¹

¹ To be published. Stage at the time of publication: prEN IEC/IEEE 63195-2:2022



IEC/IEEE 63195-1

Edition 1.0 2022-05

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body (frequency range of 6 GHz to 300 GHz) –
Part 1: Measurement procedure**

[oSIST prEN IEC/IEEE 63195-1:2022](#)

**Évaluation de la densité de puissance de l'exposition humaine aux champs radiofréquences provenant de dispositifs sans fil à proximité immédiate de la tête et du corps (plage de fréquences de 6 GHz à 300 GHz) –
Partie 1: Procédure de mesure**

INTERNATIONAL
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INTERNATIONALE

ICS 17.220.20

ISBN 978-2-8322-0123-7

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ASSESSMENT OF POWER DENSITY OF HUMAN EXPOSURE TO RADIO
FREQUENCY FIELDS FROM WIRELESS DEVICES IN CLOSE PROXIMITY
TO THE HEAD AND BODY (FREQUENCY RANGE OF 6 GHz TO 300 GHz) –****Part 1: Measurement procedure**

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